

# Seong-Jae Jeon

## List of Publications by Year in descending order

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11  
papers

159  
citations

1163117

8  
h-index

1474206

9  
g-index

11  
all docs

11  
docs citations

11  
times ranked

216  
citing authors

#	ARTICLE	IF	CITATIONS
1	A Study on the Bonding Process of Cu Bump/Sn/Cu Bump Bonding Structure for 3D Packaging Applications. Journal of the Electrochemical Society, 2010, 157, H420.	2.9	29
2	Enhanced Electrical Potential of Thermoelectric Power Waves by Sb <sub>2</sub> Te <sub>3</sub> -Coated Multiwalled Carbon Nanotube Arrays. Journal of Physical Chemistry C, 2013, 117, 913-917.	3.1	26
3	Mechanical reliability evaluation of Sn-37Pb solder joint using high speed lap-shear test. Microelectron Engineering, 2008, 85, 1967-1970.	2.4	25
4	A hybridized graphene carrier highway for enhanced thermoelectric power generation. Physical Chemistry Chemical Physics, 2012, 14, 13527.	2.8	24
5	Microstructure evolution of sputtered BiSbTe thermoelectric films during post-annealing and its effects on the thermoelectric properties. Journal of Alloys and Compounds, 2013, 553, 343-349.	5.5	19
6	A Study on the Breakdown Mechanism of an Electroless-Plated Ni(P) Diffusion Barrier for Cu/Sn/Cu 3D Interconnect Bonding Structures. Journal of Electronic Materials, 2012, 41, 109-114.	2.2	12
7	A Study on Sputtered Bi-Te Thermoelectric Films with Various Compositions: Microstructure Evolution and the Effects on Thermoelectric and Electrical Properties. Journal of Electronic Materials, 2012, 41, 60-66.	2.2	10
8	Microstructure Evolution of Sputtered Bi-Te Films during Post-Annealing: Phase Transformation and Its Effects on the Thermoelectric Properties. Journal of the Electrochemical Society, 2011, 158, H808.	2.9	9
9	Study on the contact resistance of various metals (Au, Ti, and Sb) on BiTe and SbTe thermoelectric films. Japanese Journal of Applied Physics, 2016, 55, 06JE03.	1.5	5
10	Mechanical Reliability Evaluation of Sn-37Pb/Cu and Sn-37Pb/ENIG Solder Joints by using High Speed Lap-shear Test. , 2008, , .		0
11	Introduction to the Thin Film Thermoelectric Cooler Design Theories. Journal of the Korean Society for Precision Engineering, 2014, 31, 881-887.	0.2	0